



DATA SHEET



-Product picture-

FEATURES:

- Soft, excellent compression performance
- Low thermal resistance
- Being recognized as UL94 V-0
- Viscous surface
- Being able to work under low pressure
- Excellent insulation performance and thermal resistance

APPLICATIONS:

- Between chip and heat-dissipation modules
- Optoelectronic Industry
- Netcom products
- New energy battery and vehicles industry
- Household appliances
- Wearable equipments

This series of products are environmentally compliant with RoHS 2.0, halogen, and REACH standards.

STORAGE CONDITIONS : Storage in the darkness

STORAGE TEMPERATURE : $\leq 30^{\circ}\text{C}$

STORAGE HUMIDITY : $\leq 70\%$

The height of the stacking should not be more than 7 layers and the total height should not be more than 1m.

SHELF LIFE :

Under storage conditions: 2 year

Non storage conditions: 6 months.

PROPERTIES

Items	Parameter	Unit	Test Method
Color	Pink	-	Visual
Thickness	0.3~18	mm	ASTM D 374
Hardness	10~55(±5)	Shore C	ASTM D 2240
Density	2.0(±0.5)	g/cc	ASTM D 792
Tensile Strength	≥ 0.25	Mpa	ASTM D 412
Elongation	≥ 80	%	ASTM D 412
Compression Ratio	≥ 25 (@50Psi)	%	ASTM D 575
UL Certification	V-0,5V	-	UL94
Operating Temperature	-50~180	°C	IEC 60068-2-14

THERMAL CHARACTERISTIC

Thermal conductivity	1.5(±0.2)	W/m·K	ASTM D 5470
Thermal resistance	≤ 1.5 (@20psi&1mm)	°Cin ² /W	ASTM D 5470

ELECTRICAL PROPERTIES

Breakdown voltage	≥ 8	kV /mm	ASTM D 149
Volume resistivity	$\geq 10^{10}$	$\Omega\cdot\text{cm}$	ASTM D 257
Dielectric constant	≥ 2	@1MHz	ASTM D 150
Dielectric loss	≤ 0.1	@1MHz	ASTM D 150

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